



**AI TECHNOLOGY INC**  
 70 Washington Road  
 Princeton Jct., NJ 08550  
 (609) 799-9388 fax (609) 799-9308  
 E-Mail: ait@aitechnology.com  
 Internet: http://www.aitechnology.com

**PRIMA-BOND**  
**ME7265**

**Extra Clean in Ionics**  
**Solvent-Free**  
**Electrically Insulating**  
**Thermally Conductive**

**IDEAL FOR:**  
**High Thermal Dissipation**  
**Die and Component Attach**  
**Automated Assembly**

**DESCRIPTION:**

ME7265 is a rapid curing thermally conductive and insulating epoxy adhesive for die and substrate attach applications. This paste is solvent free. It is designed for automated, inline bonding processing. Its is engineered to combine high bond strength and molecular flexibility that helps to absorb interfacial stresses for long-term reliability.

ME7265 is low in ionic impurities and meets all requirements for MIL-Std 883 Method 5011.5 specification for dielectric adhesive.

**AVAILABILITY:**

ME7265 is available in syringes for automatic needle dispense applications or in jars.

**APPLICATION PROCEDURES:**

- ( 1 ) Thaw for 30 minutes before opening jar or using syringes.
- ( 2 ) Dispense adhesive onto clean substrate with a suitable pattern to assure full die coverage.
- ( 3 ) Cure according to one of the recommended cure schedules.

**TYPICAL PROPERTIES\***

Electrical Resistivity ( 150 °C/ 30 min )	>1x10 <sup>14</sup> ohm-cm
Dielectric Strength (Volts/mil)	>750
Glass Transition Temp.(°C)	75 ±10%
Current Carrying Capabilities	
Lap-Shear Strength	>1000 psi >6.87 N/mm <sup>2</sup>
Device Push-off Strength	>2400 psi >16.6 N/mm <sup>2</sup>
Hardness (Type)	70 ( D ) ±10%
Cured Density (gm/cc)	1.8 ±10%
Thermal Conductivity	7.0 Btu-in/hr-ft <sup>2</sup> -°f ±10% 1.0 W/m-°C ±10%
Linear Thermal Expansion	45 ±15%
Coeff. (ppm/°C)	
Maximum Continuous Operation Temp. (°C)	<150
Pot Life	>7 days
Avg. Viscosity(5.0 rpm, 25°C) (Brookfield DV-1,Spindle CP51)	50,000 cp ±20%
Thixotropic Index	3.0±20%

\* Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is intended to be used in manufacturing and in the final product.

**CURE SCHEDULES:**

Temperature	Time	Pressure
	4	
100°C	hr	
125°C	90 min	
150°C	30 min	
175°C	10 min	

Ambient floor life (pot-life) is 5 days or more.

**SHELF LIFE:**

Storage temperature	Shelf Life
-40°C	12 mo

**CAUTION:** This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details.

The information contained herein is believed to be reliable. All recommendations or suggestions are made without guarantee inasmuch as conditions and methods of commercial use are beyond our control. Properties given are typical values and not intended for use in preparing specifications. The user is advised to evaluate the product in the manner the product is to be used in manufacturing and in the final product. Under no circumstance shall AI Technology be liable for accidental, consequential or other damages arising from the use or handling of this product.

While AI Technology owns all proprietary rights of material formulations of its products, specific usage in the manufacturing of certain products may involve patent rights of other companies.